

Application Serial No. 10/043898
Examiner: D. Nguyen
Art Unit: 2814

PATENT
M&G No. 10921.0110US01

In the Claims

~~Please amend the claims as follows. No new matter has been added.~~

1. (Currently Amended) A semiconductor device comprising:
a first lead having an inner portion;
a semiconductor chip mounted on the inner portion of the first lead;
a second lead having an inner portion electrically connected to the semiconductor chip;
and
a resin package for sealing the semiconductor chip together with the inner portions of the first and second leads;
wherein at least the semiconductor chip is has outer surfaces coated with a coating film formed of amorphous fluororesin.

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2. (Currently Amended) The semiconductor device according to claim 1, wherein the semiconductor chip is electrically connected to the inner portion of the second lead via a wire, the coating film on the outer surfaces of the semiconductor chip also covering the wire and the inner portions of the first and second leads.

3. (Original) The semiconductor device according to claim 1, wherein the amorphous fluororesin is PTFE.

4. (Original) The semiconductor device according to claim 1, wherein the coating film has a thickness of 5-50 μ m.

5. (Original) The semiconductor device according to claim 1, wherein the semiconductor chip is an LED chip.

6. (Original) The semiconductor device according to claim 1, wherein the resin package is formed of a transparent resin.

Claims 7-12 (Canceled without prejudice or disclaimer)